CARRIER ASSEMBLIES



For fast, accurate placement of SIP sockets and ultra-low profile terminals









Phase 1: Receive Carrier Assemblies designed to your pin layout.

Before Soldering



Phase 2:

Place carrier assemblies onto PCB; run through your soldering process.



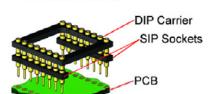
Phase 3:

Remove carrier and plug in your device; discard carrier or send back to our factory for reloading.

DIP

During Soldering

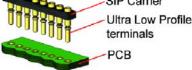




ULTRA-LOW PROFILE SIP

During Soldering After Soldering







ULTRA-LOW PROFILE PGA



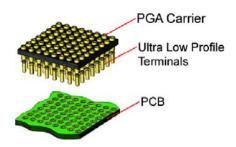
Before Soldering

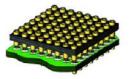
Before Soldering

Before Soldering

During Soldering

After Soldering



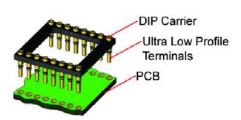


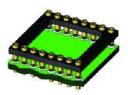


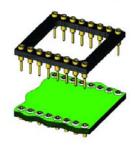
ULTRA LOW PROFILE DIP

During Soldering

After Soldering







©Copyright 2018 Andon Electronics Corporation. All Rights Reserved. This material is protected under US and other copyrights and may not be copied, sold, or redistributed in any form without written permission of Andon Electronics Corporation. Copyrights and trademarks are property of their respective companies. We reserve the right to change specifications without notice. Andon makes no warranty, expressed or implied, as to the suitability of the sockets for the intended purpose.

"ANDON PROPRIETARY INFORMATION" RoHS Compliant IS-14B 07/20/2018